

UltraSlic™ FG Stencil Foil

UltraSlic™ FG Foil was developed to offer superior fatigue strength, a super smooth printing surface and improved wear factors. The fine grain structure allows for superior aperture registration and repeatable paste release.

No. 1 FOR PERFORMANCE

Our obsession with print performance and data has resulted in $UltraSlic^{TM}$ FG, our most innovative SMT stencil material yet. Our goal was simple; deliver a true cost reduction without compromising performance.

We wanted to create a product that would laser cut and print like Slic[™] plus offer the flexibility to work in all stencil types including meeting the emerging demand for High Tension Stencils.

We did it. Which is why our data says yes!

- UltraSlic[™] stencils product the highest print yields
- Available in all the BlueRing thickness and width formats
- Manufactured with end-to-end process control and data capture
- Reduces noise and variability in the print process

PRODUCT SELECTOR GUIDE

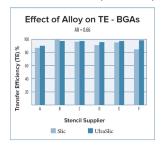
	Slic	UltraSlic FG
Miniaturised or high-density assembly		•
Area ratios <0.60		•
General SMT, lead pitches≥ 0.5mm, leadless pitches≥ 1.0mm	•	٠
Stepped stencil for µBGA, CSP, QFN, BTC		•
Uniform foil thickness ≥150µm	•	•
Powder Size Type: 5, 6		•
Powder Size Type: 3, 4	•	•

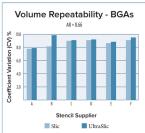
SPECIFICATIONS

- Gauges: 0.02 to 0.500 (0.8 mil to 12 mil)
- Sizes: Widths from 100mm to 690mm
- Availability: Worldwide

WALL SMOOTHNESS

- Smooth walls enable better solder paste fill and release
- Drops into current processes without requiring parameter adjustments
- Laser cuts cleanly and easily

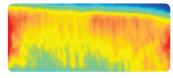




WALL ROUGHNESS COMPARISON

Holographic Microscopy

Cut with the same laser parameters, the best performer





Slic™

UltraSlic[™] Fine Grain

TOUGHER STEEL

- Can carry high tension without stretching to maintain precise registration with PCB
- Stronger, stiffer webs limit spring back to produce crisper prints

QUALITY COMMITMENT

- Right first time, every time
- Excel and lead in customer service and technical support
- Continuous process improvement